# High Speed Infrared Emitting Diodes, 890 nm, GaAlAs, DH

VSMF288011RGX01

VSMF288011GX01

## FEATURES

- Package type: surface-mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- AEC-Q101 qualified
- Peak wavelength: $\lambda_p$ = 890 nm
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity: $\varphi$ = ± 11°
- Low forward voltage
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reserve gullwing
- Package matches with detector VEMD2000X01 series
- Floor life: 4 weeks, MSL 2a, according to J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

AUTOMOTIVE GRADE

Pb-free

e3

RoHS COMPLIANT

HALOGEN FREE

GREEN (5-2008)

## DESCRIPTION

VSMF288011RG(G)X01 series are infrared, 890 nm emitting diodes in GaAlAs (DH) technology with high radiant power, high speed and typical receiving characteristics. VSMF288011RG(G)X01 is molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

## APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Metering

**PRODUCT SUMMARY**

| COMPONENT | $I_e$ (mW/sr) | $\varphi$ (°) | $\lambda_p$ (nm) | $t_r$ (ns) |
|---|---|---|---|---|
| VSMF288011RGX01 | 36 | ± 11 | 890 | 50 |
| VSMF288011GX01 | 36 | ± 11 | 890 | 50 |

**Note**

- Test conditions see table “Basic Characteristics“

**ORDERING INFORMATION**

| ORDERING CODE | PACKAGING | REMARKS | PACKAGE FORM |
|---|---|---|---|
| VSMF288011RGX01 | Tape and reel | MOQ: 6000 pcs, 6000 pcs/reel | Reverse gullwing |
| VSMF288011GX01 | Tape and reel | MOQ: 6000 pcs, 6000 pcs/reel | Gullwing |

**Note**

- MOQ: minimum order quantity

| **ABSOLUTE MAXIMUM RATINGS** ($T_{amb}$ = 25 °C, unless otherwise specified) | | | | |
|---|---|---|---|---|
| **PARAMETER** | **TEST CONDITION** | **SYMBOL** | **VALUE** | **UNIT** |
| Reverse voltage | | $V_R$ | 5 | V |
| Forward current | | $I_F$ | 100 | mA |
| Peak forward current | $t_p/T$ = 0.5, $t_p$ = 100 µs | $I_{FM}$ | 200 | mA |
| Surge forward current | $t_p$ = 100 µs | $I_{FSM}$ | 1 | A |
| Power dissipation | | $P_V$ | 190 | mW |
| Junction temperature | | $T_j$ | 100 | °C |
| Operating temperature range | | $T_{amb}$ | -40 to +85 | °C |
| Storage temperature range | | $T_{stg}$ | -40 to +100 | °C |
| Soldering temperature | According to Fig. 9, J-STD-020 | $T_{sd}$ | 260 | °C |
| Thermal resistance junction-to-ambient | J-STD-051, leads 7 mm, soldered on PCB | $R_{thJA}$ | 250 | K/W |

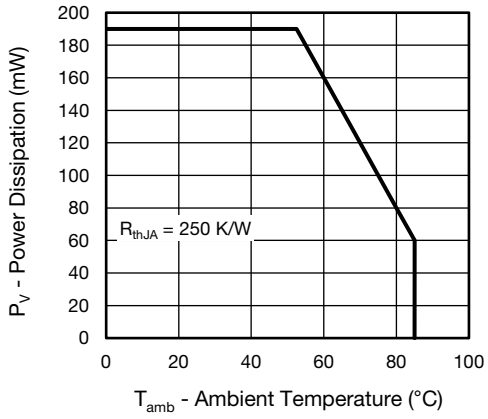



Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

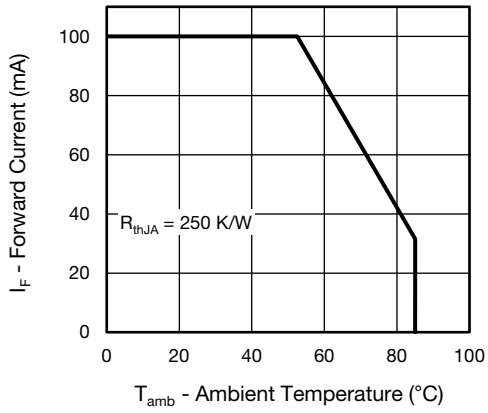



Fig. 2 - Forward Current Limit vs. Ambient Temperature

| **BASIC CHARACTERSITICS** ($T_{amb}$ = 25 °C, unless otherwise specified) | | | | | | |
|---|---|---|---|---|---|---|
| **PARAMETER** | **TEST CONDITION** | **SYMBOL** | **MIN.** | **TYP.** | **MAX.** | **UNIT** |
| Forward voltage | $I_F$ = 100 mA, $t_p$ = 20 ms | $V_F$ | - | 1.6 | 1.9 | V |
| | $I_F$ = 200 mA, $t_p$ = 100 µs | $V_F$ | - | 1.9 | 2.5 | V |
| Temperature coefficient of $V_F$ | $I_F$ = 100 mA | $TK_{VF}$ | - | -1.1 | - | mV/K |
| Reverse current | $V_R$ = 5 V | $I_R$ | - | - | 10 | µA |
| Junction capacitance | $V_R$ = 0 V, f = 1 MHz, E = 0 mW/cm² | $C_J$ | - | 65 | - | pF |
| Radiant intensity | $I_F$ = 100 mA, $t_p$ = 20 ms | $I_e$ | 18 | 36 | 70 | mW/sr |
| Reverse light current | $E_e$ = 1 mW/cm², λ = 870 nm, $V_R$ = 5 V | $I_{ra}$ | - | 6.4 | - | µA |
| Radiant power | $I_F$ = 100 mA, $t_p$ = 20 ms | $\phi_e$ | - | 30 | - | mW |
| Temperature coefficient of $\phi_e$ | $I_F$ = 100 mA | $TK\phi_e$ | - | -0.35 | - | %/K |
| Angle of half intensity | | φ | - | ± 11 | - | ° |
| Peak wavelength | $I_F$ = 100 mA | $\lambda_p$ | 870 | 890 | 910 | nm |
| Spectral bandwidth | $I_F$ = 100 mA | Δλ | - | 40 | - | nm |
| Temperature coefficient of $\lambda_p$ | $I_F$ = 100 mA | $TK\lambda_p$ | - | 0.33 | - | nm/K |
| Rise time | $I_F$ = 100 mA, 20 % to 80 % | $t_r$ | - | 50 | - | ns |
| Fall time | $I_F$ = 100 mA, 20 % to 80 % | $t_f$ | - | 50 | - | ns |

**BASIC CHARACTERSITICS** ($T_{amb}$ = 25 °C, unless otherwise specified)

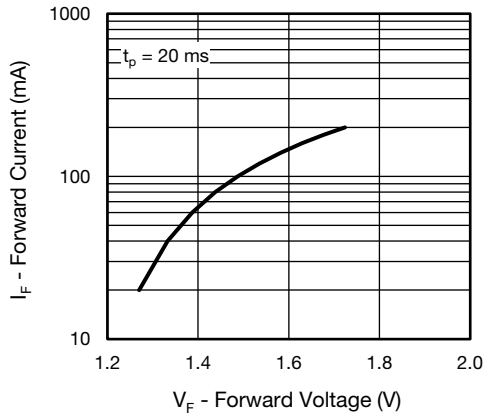



Fig. 3 - Forward Current vs. Forward Voltage

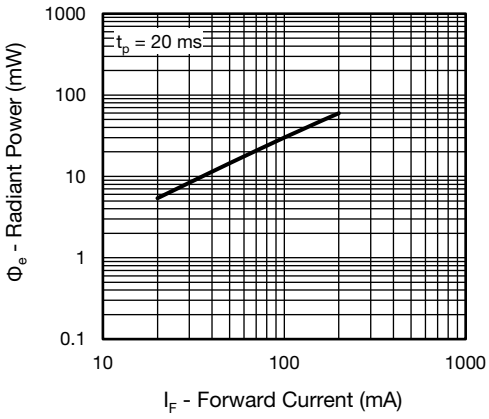



Fig. 6 - Radiant Power vs. Forward Current

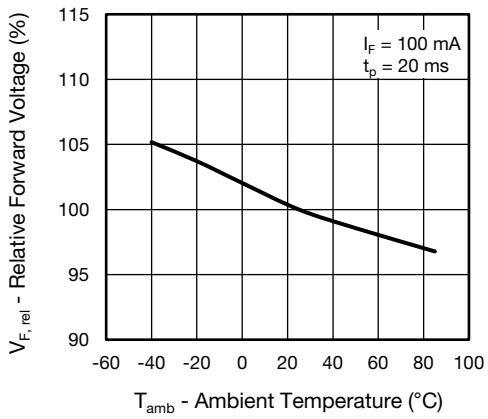



Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

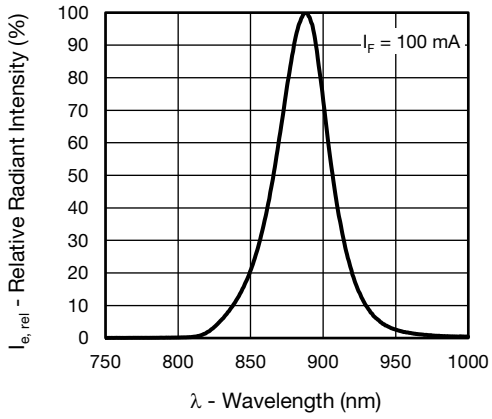



Fig. 7 - Relative Radiant Power vs. Wavelength

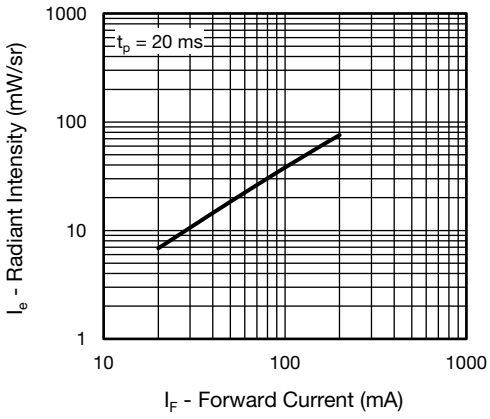



Fig. 5 - Radiant Intensity vs. Forward Current

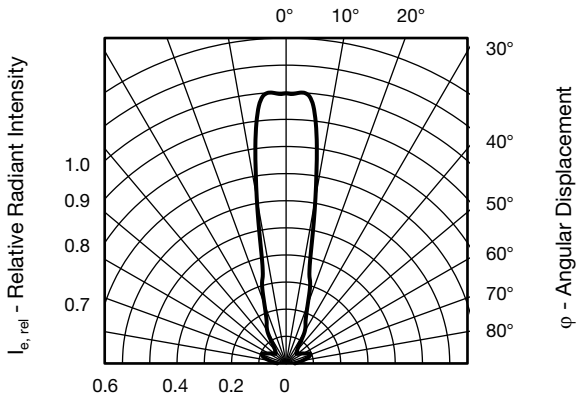



Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

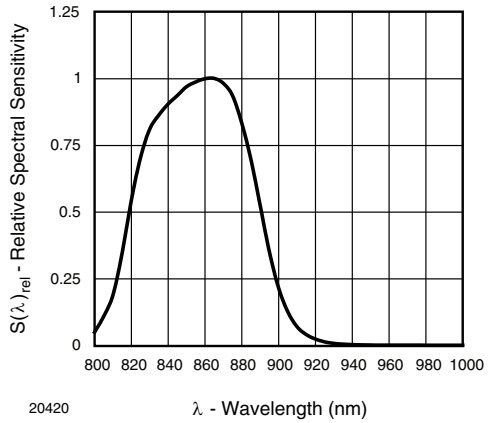



Fig. 9 - Relative Spectral Sensitivity vs. Wavelength

## SOLDER PROFILE

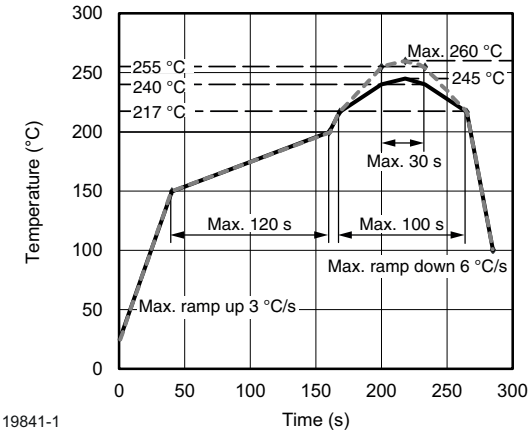



Fig. 10 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

## DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

## FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

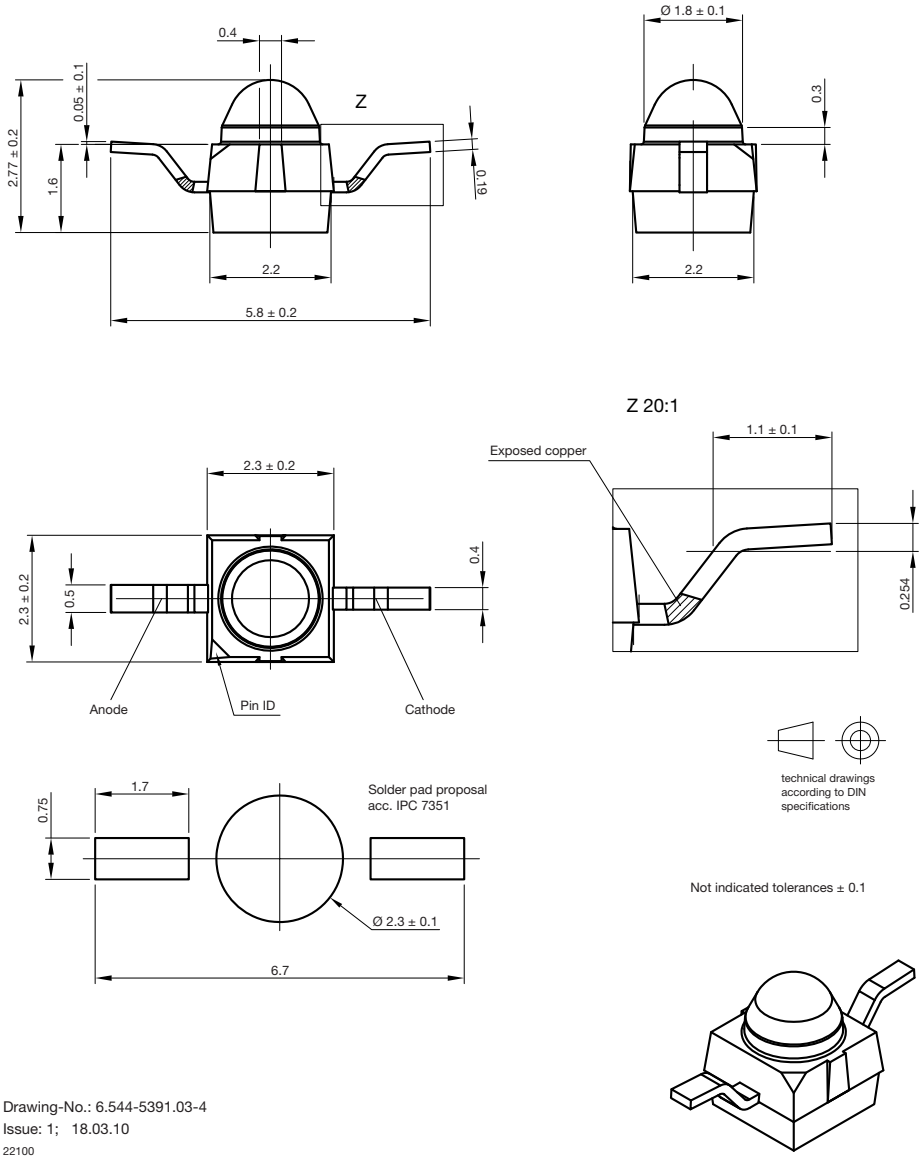
Conditions: $T_{amb}$ < 30 °C, RH < 60 %

Moisture sensitivity level 2a, acc. to J-STD-020.

## DRYING

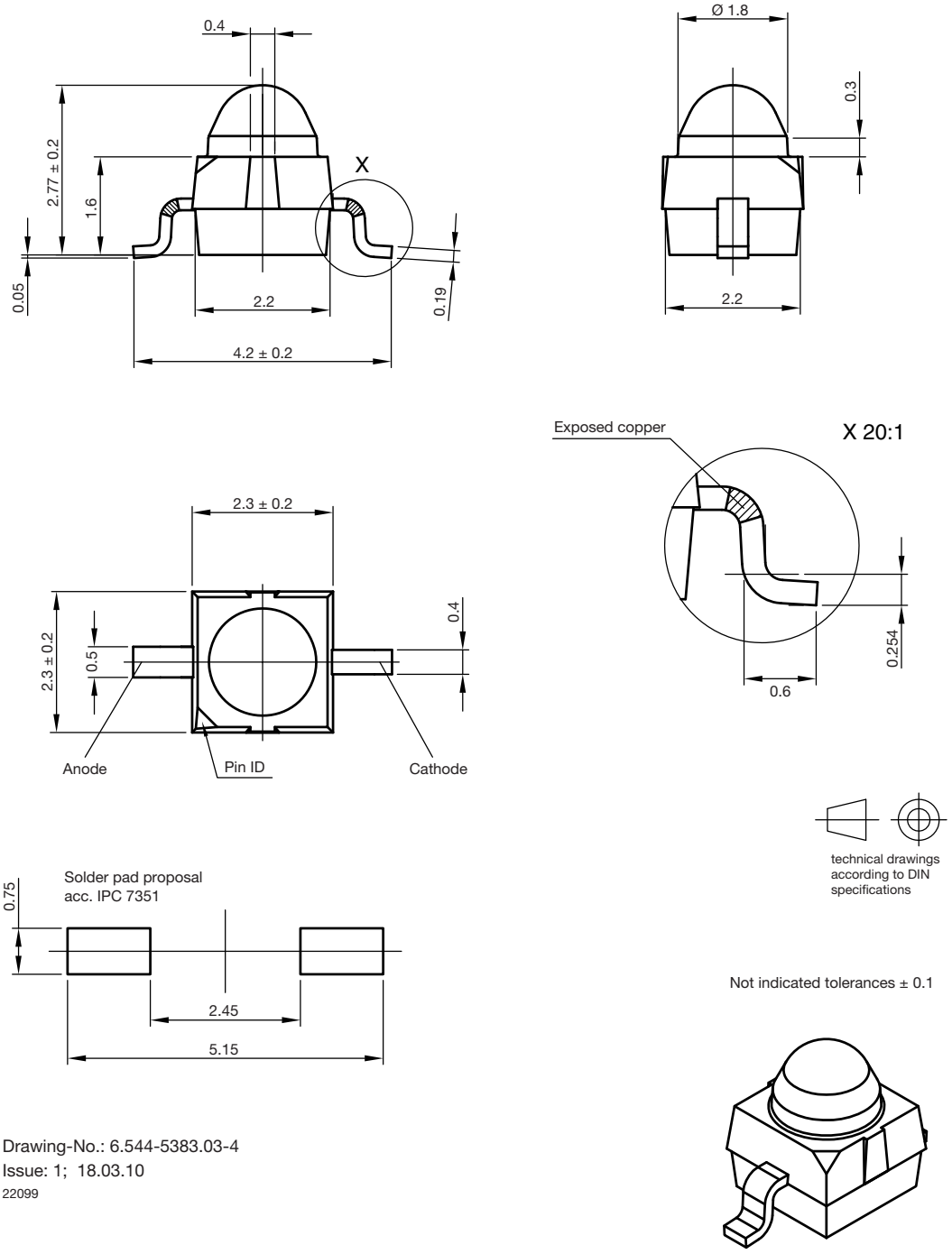
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

**PACKAGE DIMENSIONS** in millimeters: **VSMF288011RGX01**



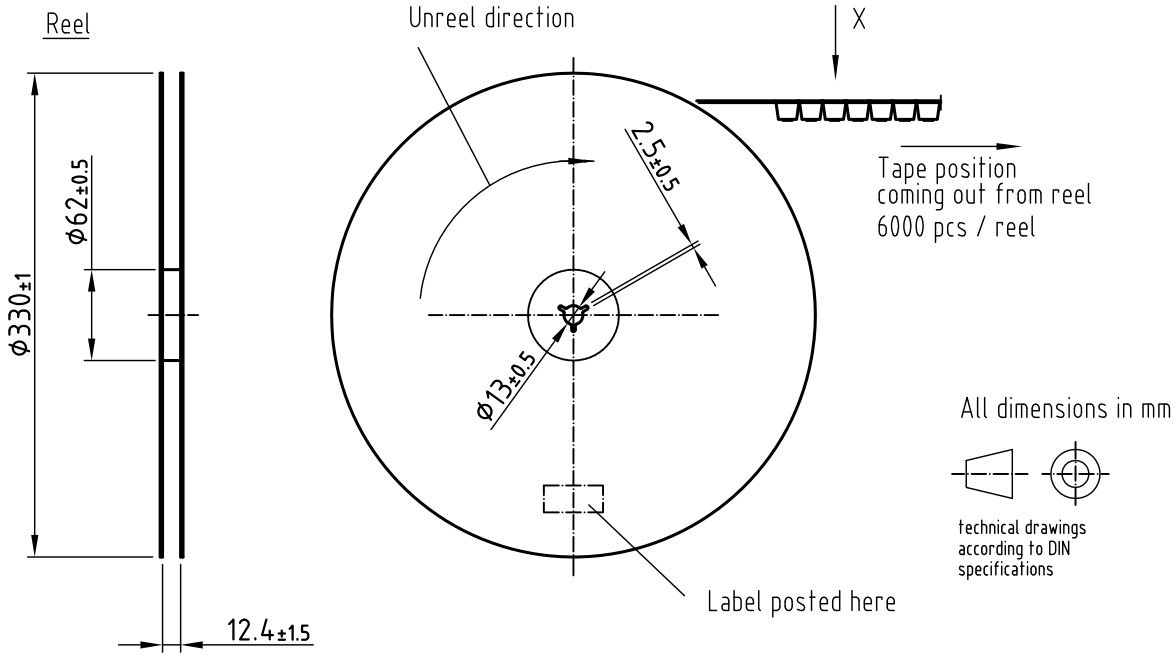

Drawing-No.: 6.544-5391.03-4
Issue: 1; 18.03.10
22100

**PACKAGE DIMENSIONS** in millimeters: **VSMF288011GX01**

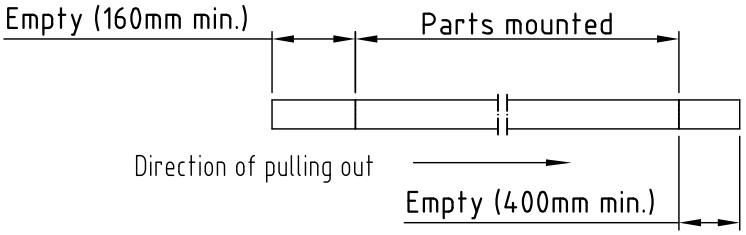


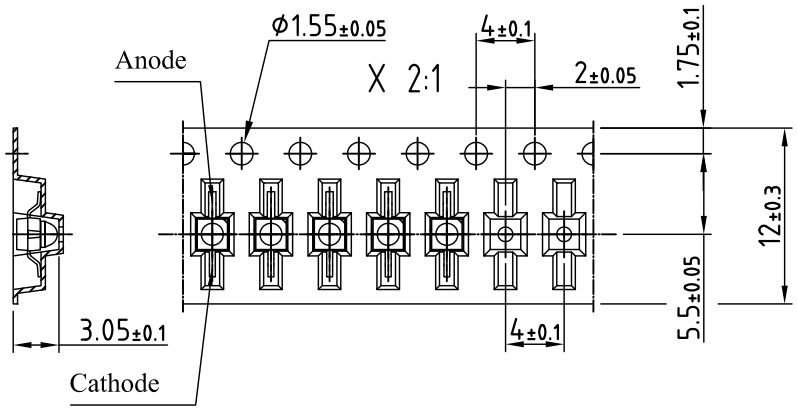

Drawing-No.: 6.544-5383.03-4
Issue: 1; 18.03.10
22099

**TAPING AND REEL DIMENSIONS** in millimeters: **VSMF288011RGX01**

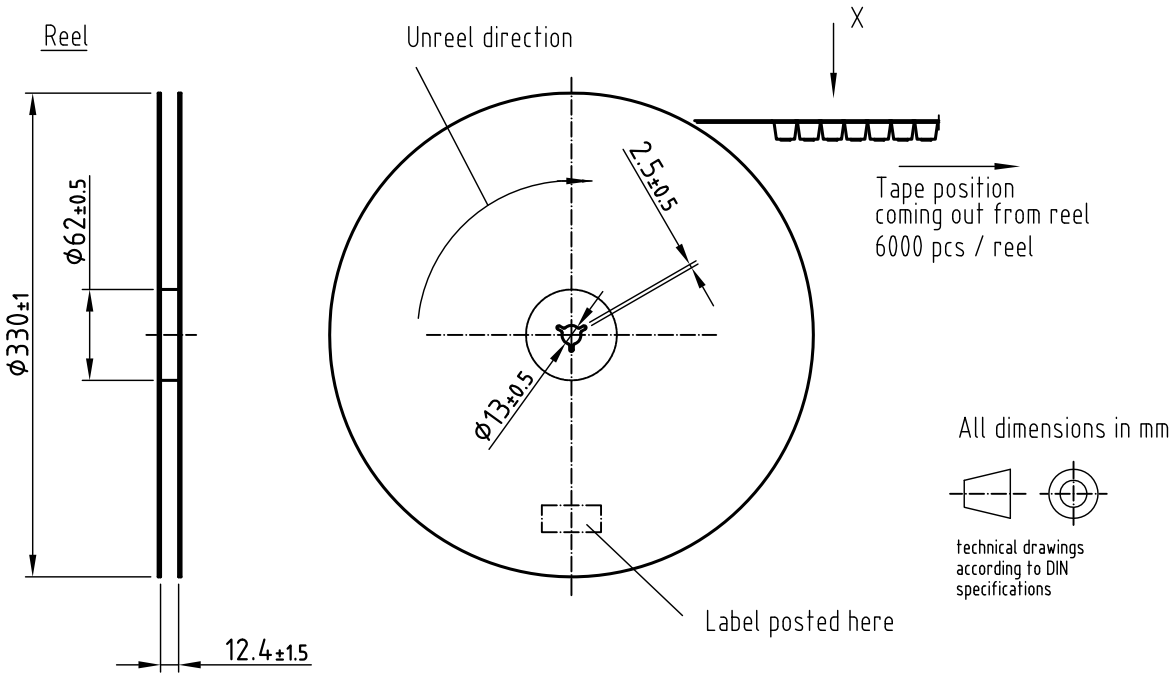



Leader and trailer tape:



**TAPING AND REEL DIMENSIONS** in millimeters: **VSMF288011GX01**

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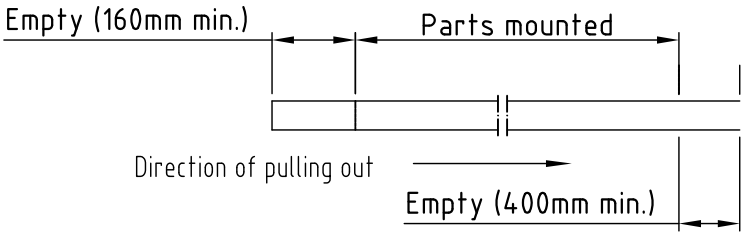


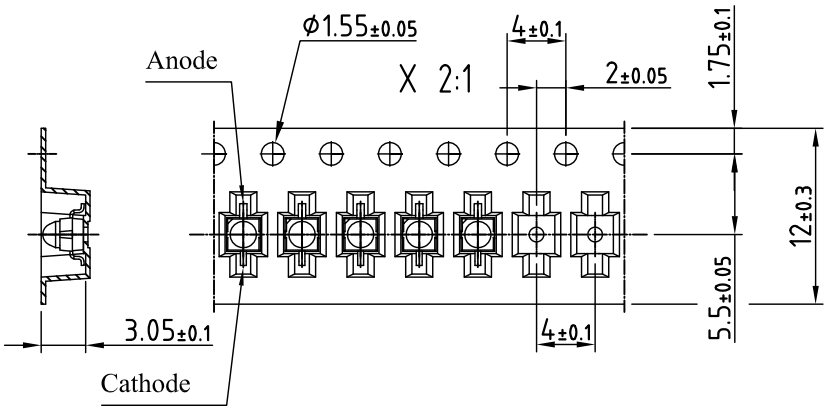

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